CLAIMS

1. A cover tape for electronic component packaging, comprising a heat sealant layer on a base layer, wherein said heat sealant layer contains polyolefin resin and polyether-polyolefin copolymer.

2. The cover tape for electronic component packaging according to claim 1, wherein the weight ratio of the polyether-polyolefin copolymer in said heat sealant layer is 10 weight % or more and 70 weight % or less.

3. The cover tape for electronic component packaging according to claim 2, wherein the weight ratio of the polyether-polyolefin copolymer in said heat sealant layer is 20 weight % or more and 50 weight % or less.

4. The cover tape for electronic component packaging according to any of the claims 1-3, wherein a melt flow rate (measurement method: JIS K6921-2 - measurement conditions: temperature 190°C, load 21.18 N) of said polyether-polyolefin copolymer is 10-35 g/10 min.

5. The cover tape for electronic component packaging according to any of the claims 1-4, wherein said polyolefin resin is one or more resins selected from a group consisting of polyethylene, polypropylene, ethylene-vinyl acetate copolymer, ethylene-(meth)acrylic acid copolymer, ethylene-methyl (meth)acrylate copolymer, ethylene-methyl acrylate copolymer, ethylene-ethyl acrylate copolymer, and ethylene-butyl acrylate copolymer.

6. The cover tape for electronic component packaging according to any of the claims 1-5, wherein said polyether-polyolefin copolymer is a block copolymer.

7. The cover tape for electronic component packaging according to claims 1-6, wherein said heat sealant layer also contains polystyrene resin.

8. The cover tape for electronic component packaging according to any of the claims 1-5, which has one or more intermediate layers between said base layer and heat sealant layer.

9. The cover tape for electronic component packaging according to claim 8, wherein said intermediate layer contains an antistatic agent.

10. The cover tape for electronic component packaging according to claim 9, wherein said antistatic agent contains propylene carbonate and a surfactant.

11. The cover tape for electronic component packaging according to claim 9 or 10, wherein the surface resistance value (measurement method: JIS K6911 - measurement conditions: humidity 30% RH, temperature 23°C) of the intermediate layer containing said antistatic agent is less than 1.0 E + 12 Ω.

12. The cover tape for electronic component packaging according to claim 10, wherein said surfactant is a cationic surfactant.

13. The cover tape for electronic component packaging according to claim 12, wherein said cationic surfactant is alkyl quaternary ammonium ethosulfate.

14. An electronic component package obtained by heat sealing the cover tape for electronic component packaging according to any of the claims 1-13 and carrier tape for electronic component packaging, wherein said heat sealant layer and said carrier tape are heat sealed in a prescribed region.

15. The electronic component package according to claim 14, wherein a peeling charge during peeling of said cover tape for electronic component packaging from said carrier tape for electronic component packaging is 300 V or less.

CLAIMS

1. A cover tape for electronic component packaging, comprising a heat sealant layer on a base layer, wherein

said heat sealant layer contains a first resin and a second resin, wherein the first resin is a polyolefin resin and the second resin is a polyether-polyolefin copolymer; and

the heat sealant layer further contains styrene methyl (meth)acrylate copolymers.

2. The cover tape for electronic component packaging according to claim 1, wherein the weight ratio of the polyether-polyolefin copolymer in said heat sealant layer is equal to or more than 10 weight % and equal to or less than 70 weight %.

3. The cover tape for electronic component packaging according to claim 2, wherein the weight ratio of the polyether-polyolefin copolymer in said heat sealant layer is equal to or more than 20 weight % and equal to or less than 50 weight %.

4. The cover tape for electronic component packaging according to any of the claims 1-3, wherein a melt flow rate of said polyether-polyolefin copolymer is 10-35 g/10 min, and the melt flow rate is measured by JIS K6921-2 at a temperature of 190°C and a load of 21.18 N.

5. The cover tape for electronic component packaging according to any of the claims 1-4, wherein said polyolefin resin is one or more resins selected from a group consisting of polyethylene, polypropylene, ethylene-vinyl acetate copolymer, ethylene-(meth)acrylic acid copolymer, ethylene-methyl (meth)acrylate copolymer, ethylene-methyl acrylate copolymer, ethylene-ethyl acrylate copolymer, and ethylene-butyl acrylate copolymer.

6. The cover tape for electronic component packaging according to any of the claims 1-5, wherein said polyether-polyolefin copolymer is a block copolymer.

7. The cover tape for electronic component packaging according to any of the claims 1-5, which has one or more intermediate layers between said base layer and heat sealant layer.

8. The cover tape for electronic component packaging according to claim 7, wherein said intermediate layer contains an antistatic agent.

9. The cover tape for electronic component packaging according to claim 8, wherein said antistatic agent contains propylene carbonate and a surfactant.

10. The cover tape for electronic component packaging according to claim 8 or 9, wherein the surface resistance value of the intermediate layer containing said antistatic agent is less than 1.0 E + 12 Ω, and the surface resistance value is measured by JIS K6911 at a humidity of 30% RH and a temperature of 23°C.

11. The cover tape for electronic component packaging according to claim 9, wherein said surfactant is a cationic surfactant.

12. The cover tape for electronic component packaging according to claim 11, wherein said cationic surfactant is alkyl quaternary ammonium ethosulfate.

13. An electronic component package obtained by heat sealing the cover tape for electronic component packaging according to any of the claims 1-12 and a carrier tape for electronic component packaging, wherein said heat sealant layer and said carrier tape are heat sealed in a prescribed region.

14. The cover tape for electronic component packaging according to any one of the claims 1 to 12, wherein said heat sealant layer consists essentially of the polyolefin resin, the polyether-polyolefin copolymer, and the styrene methyl (meth)acrylate copolymer.